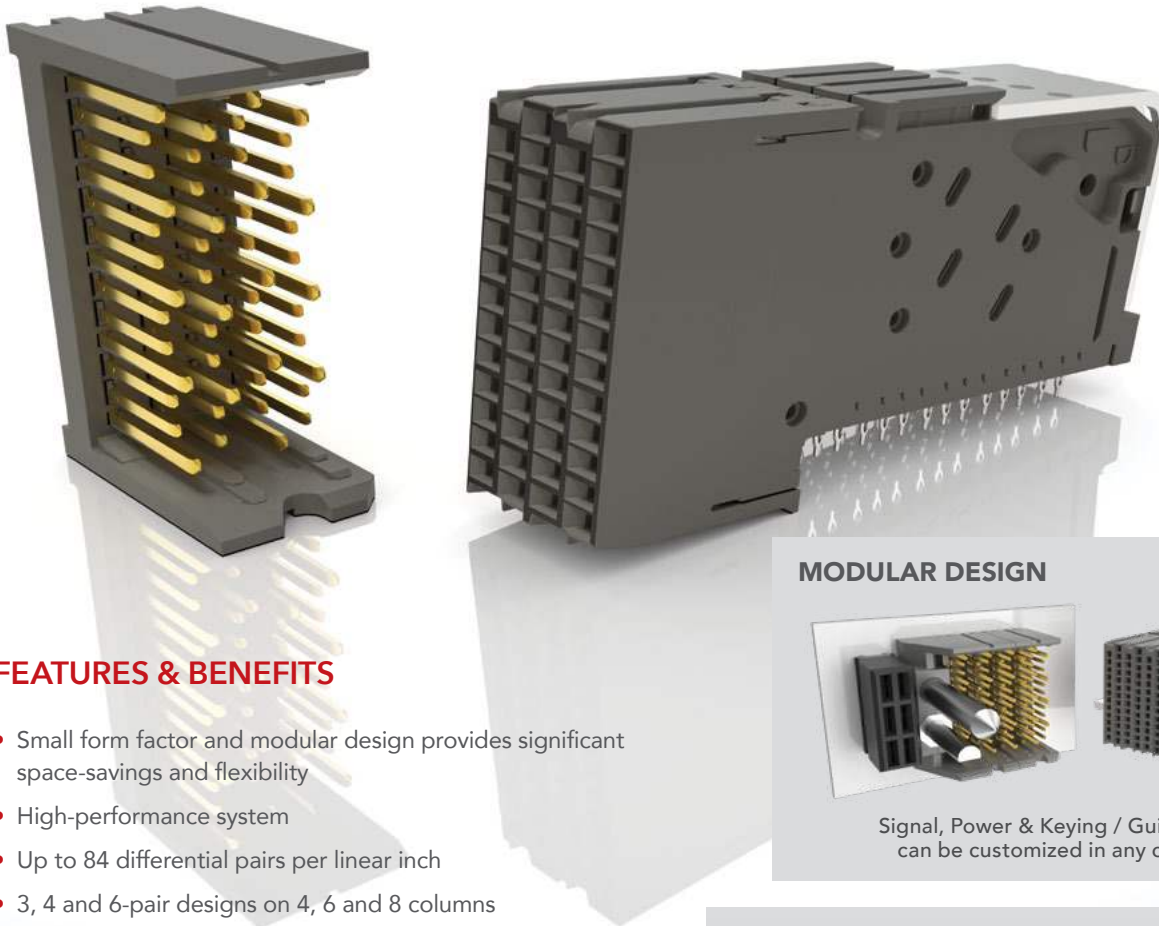


HIGH-DENSITY BACKPLANE HEADERS & SOCKETS

(1.80 mm) .071" PITCH

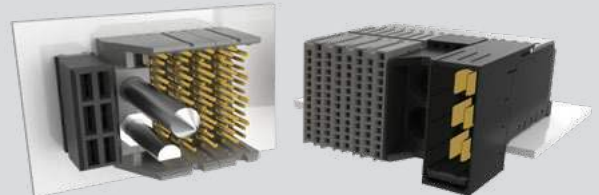
16
Gbps



FEATURES & BENEFITS

- Small form factor and modular design provides significant space-savings and flexibility
- High-performance system
- Up to 84 differential pairs per linear inch
- 3, 4 and 6-pair designs on 4, 6 and 8 columns
- Integrated power, guidance, keying and end walls available
- 85 Ω and 100 Ω options
- Combine any configuration of modules to create one integrated receptacle (BSP Series); corresponding terminal modules are individually mounted to the backplane
- Press-fit extraction and insertion tool options; please visit samtec.com/tooling for details

MODULAR DESIGN



Signal, Power & Keying / Guidance options can be customized in any configuration

HIGH-DENSITY, SMALL FORM FACTOR



XCede[®] HD
Up to 84 pairs per linear inch



Traditional Backplane
Up to 76 pairs per linear inch

(Both shown with six 4-pair, 8 column receptacles)

KEY SPECIFICATIONS

PITCH	INSULATOR MATERIAL	CONTACT MATERIAL	PLATING	OPERATING TEMP RANGE
1.80 mm	LCP	Phosphor Bronze (HDTM Series) Copper Alloy (HDTF & HPTS Series)	Au or Sn over 50 μ" (1.27 μm) Ni	-40 °C to + 105 °C (HDTX Series)

XCede HD

(1.80 mm) .071" PITCH • HIGH-DENSITY BACKPLANE RECEPTACLE

HDTF	PAIRS PER COLUMN	NO. OF COLUMNS	PLATING	RA	WAFERS	IMPEDANCE
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-3, -4, -6

-04, -06, -08

-S
= 30 μ" (0.76 μm)
Gold on Contact Area,
Matte Tin on Tail

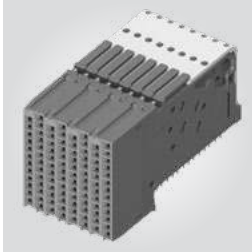
-LC
= Standard

-100
= 100 Ω

-HS
= High-Speed

-085
= 85 Ω

HDTF
Board Mates:
HDTM

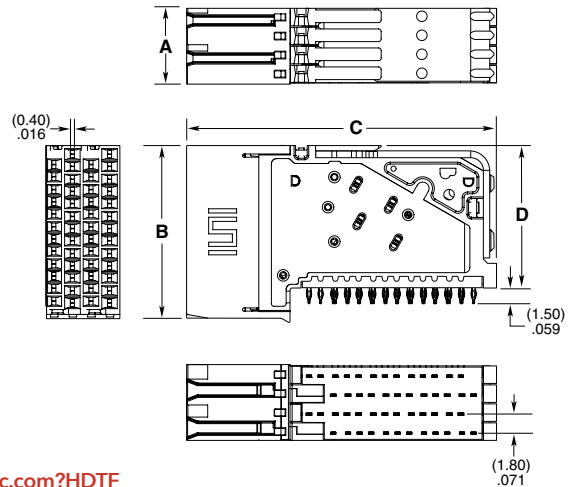


NO. OF COLUMNS	A
-04	(7.2) .28
-06	(10.8) .42
-08	(14.4) .57

PAIRS PER COLUMN	B	C	D
-3	(12.8) .50	(26.0) 1.02	(9.8) .386
-4	(16.4) .64	(29.4) 1.16	(13.5) .53
-6	(23.6) .93	(36.6) 1.44	(20.7) .81

ALSO AVAILABLE

Power and keying/
guidance modules
also are available
but require a single
customizable BSP
product. Contact
HSBP@samtec.com.



View complete specifications at: samtec.com?HDTF

(3.20 mm) .126" PITCH • HIGH-DENSITY BACKPLANE POWER MODULE

HPTS	BODY HEIGHT	PLATING	D	ORIENTATION
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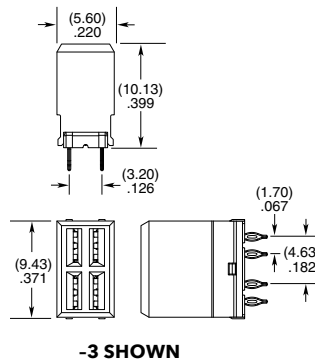
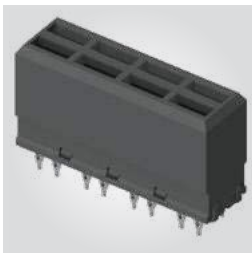
Based on Pair Count of Signal Modules (HDTF Series).

- 3** = For use with 3 pair HDTF Series
- 4** = For use with 4 pair HDTF Series
- 6** = For use with 6 pair HDTF Series

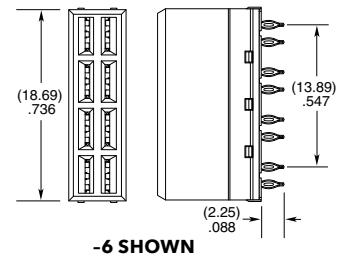
-S
= Standard Gold on Contact Area,
Matte Tin on Tail

-VT
= Vertical

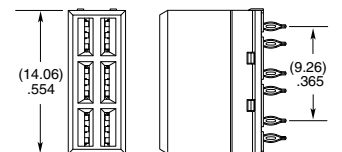
HPTS
Mates with:
BSP
(See HDTF
for more
information.)



-3 SHOWN



-6 SHOWN



-4 SHOWN

Notes:
Some lengths, styles and options are non-standard, non-returnable. XCede® is a registered trademark of Amphenol.

View complete specifications at: samtec.com?HPTS